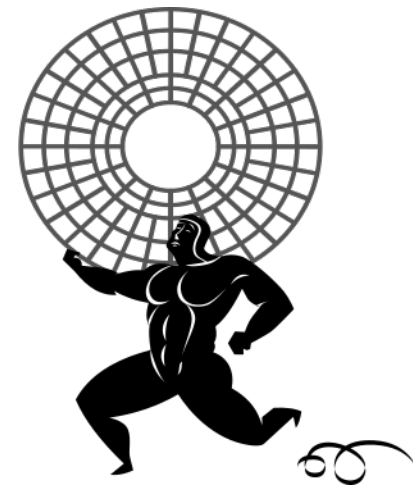


Procedures

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List of items for R0 (continued)

- Shipping

- We will need to ship different items around
 - Hybrids, powerboards, sensors, modules
 - Some are delicate, some not
 - Some have already their shipping method (sensors)
- Transport boxes
 - Hybrids, needed. Freiburg ?
 - Modules, needed.
 - First prototype ready and will be presented here.
 - How many will be needed ?
 - Will the manufacturing be centralised or distributed ?
 - Other transport boxes ?

List of items for R0 (continued)

- DAQ setup
 - Is this covered in another session ?
 - All testing labs have already a setup ?
 - Guideline to define what connects to what and software configuration
 - I think it exists
 - We should adapt it to R0, and add list of known problems and solutions

DOCUMENTATION

- Description documents (engineering) : more or less existent
 - Hybrids
 - Powerboards
 - Test frames
 - Other ? (wirebonding maps, component datasheets)
 - We have been using twiki to centralise them. Should we make the twiki page as the central point to acces all documentation ?
- Test documents: guide with a list of the electrical test to be done to each item
 - Sensor
 - Hybrid
 - Powerboard
 - Module
 - I haven't seen them, probably they don't exist. Need to generate this documentation with pass/fail criteria. (Probably covered in hybrid, sensor, powerboard, QA sessions).



DOCUMENTATION (continued)

- Assembly documents: procedure document with step by step instructions.
 - Chips to hybrid
 - Hybrid and powerboard to sensor
 - Wirebonding programs ?
 - QC covered in other session, but it should have the corresponding documentation

SEMI-ELECTRICAL PETAL

- Most of the previous procedures for R0 should be valid for hybrid-to-dummy sensor R1-R5 modules
 - Keep an eye on the needed tooling
 - We should provide the corresponding documentation
- In addition we should take care of the procedures and documentation of:
 - Core manufacturing and Core assembly (talk tomorrow)
 - Bustape
 - R1-R5 Hybrid (covered in hybrids discussion ?)
 - R1-R5 dummy sensor (covered in sensors discussion ?)
 - Module to core assembly
 - EoS